

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6855572".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 10:58
L2	2	"5266833".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 10:58
L3	2	"20030230802"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 10:58

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"5138115".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 12:11
L2	214542	(semiconductor chip die ic component (integrated adj circuit)) with (recessed recess recessing semicylindrical semi cylindrical cylindrically)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 12:13
L3	6180	(semiconductor chip die ic component (integrated adj circuit)) with (recessed recess recessing) with (semicylindrical semi cylindrical cylindrically)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 12:14
L4	662	(electrode terminal pad) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 12:15
L5	36415	(semiconductor chip die ic component (integrated adj circuit)) with (peripheral peripherally edge side outer recessed recess recessing) with (semicylindrical semi cylindrical cylindrically)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 12:15
L6	65871	(semiconductor chip die ic component (integrated adj circuit)) with (peripheral peripherally edge side outer recessed recess recessing) with (semicylindrical semi cylindrical cylindrically half circle circular)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 12:15
L7	7634	(electrode terminal pad) same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 12:15
L8	458	(packaging package packaged) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 12:17

L9	3274	(trace metal conductive conductor) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 12:17
L10	534	(packaging package packaged) and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 12:17